

L Number	Hits	Search Text	DB	Time stamp
1	1773	"bonded structure"	USPAT	2004/06/11 15:40
2	29	"bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.	USPAT	2004/06/11 16:36
4	27	("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)	USPAT	2004/06/11 16:57
5	26	((("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared or ir)	USPAT	2004/06/11 15:45
6	24	((("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared or ir)) and (sens\$ or detect\$ or measur\$).detd.	USPAT	2004/06/11 15:55
7	27	((("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared or ir or temperature)	USPAT	2004/06/11 15:45
8	25	((("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared or ir or temperature)) and (sens\$ or detect\$ or measur\$).detd.	USPAT	2004/06/11 15:54
9	5	((("bonded structure" and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)) and (heat or thermal or infrared or ir or temperature)) and ((sens\$ or detect\$ or measur\$) near2 (heat or thermal or temperature)).detd.	USPAT	2004/06/11 16:24
10	0	((manufactur\$ near3 substrate\$1) and ((facility or factory) with (alert\$ or alarm\$ or warn\$) with (temperature or heat or gas))).detd.	USPAT	2004/06/11 16:33
11	301	((manufactur\$ near3 (substrate\$1 or wafer\$1 or semicondcutor\$1)) and ((substrate\$1 or wafer\$1 or semicondcutor\$1) with ((temperature or heat or gas or environment\$) near2 (sens\$ or detect\$ or measur\$))).detd.	USPAT	2004/06/11 16:35
12	50	((manufactur\$ near3 (substrate\$1 or wafer\$1 or semicondcutor\$1)) and ((substrate\$1 or wafer\$1 or semicondcutor\$1) with ((temperature or heat or gas or environment\$) near2 (sens\$ or detect\$ or measur\$))).detd.) and (facility or factory or manufacturer).detd.	USPAT	2004/06/11 16:35
13	1	((((manufactur\$ near3 (substrate\$1 or wafer\$1 or semicondcutor\$1)) and ((substrate\$1 or wafer\$1 or semicondcutor\$1) with ((temperature or heat or gas or environment\$) near2 (sens\$ or detect\$ or measur\$))).detd.) and (facility or factory or manufacturer).detd.) and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.	USPAT	2004/06/11 16:36

14	1	(((manufactur\$ near3 (substrate\$1 or wafer\$1 or semicondcutor\$1)) and ((substrate\$1 or wafer\$1 or semicondcutor\$1) with ((temperature or heat or gas or environment\$) near2 (sens\$ or detect\$ or measur))))).detd.) and (facility or factory or manufacturer).detd.) and (((circuit near board) or substrate) and (borosilicate or rbm)).detd.) and (oxygen or oxide or oxidiz\$)	USPAT	2004/06/11 16:57
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